

# MATERIAL DECLARATION SHEET

**BOURNS®**

Material Number	CD143A Series				
Product Line	Diode Products				
Compliance Date	13 July 2008				
RoHS Compliant	Yes	MSL	1		

No.	Construction Element(subpart)	Homogeneous Material	Material weight [g]	Homogeneous Material\ Substances	CASRN if applicable	Materials Mass %	Material Mass % of total unit wt.	Subpart mass of total wt. (%)
1	Lead Frame	Lead Frame	0.017090	Copper	7440-50-8	95	40.770	42.830
				Tin	7440-31-5	5	2.0600	
2	Die	Silicon	0.010036	Silicon	7440-21-3	97	23.420	23.9
				Misc. not to disclose	N/A	2	0.4780	
3	Gold Bond Wire	Conductor	0.000234	Gold	7440-57-5	100	0.5867	0.5867
4	Silver Paste	Die Attach	0.000540	Silver	7440-22-4	77	1.05	1.3470
				Epoxy	9003-36-5	21	0.2963	
5	Molding Component	Outer	0.012000	Silica fused	60676-86-0	85	26.690	31.400
				Epoxy resin	68928-70-1	10	3.1400	
				Phenol resin	29690-82-2	6	1.8840	
		Total weight	0.039964					

This Document was updated on: June 12, 2018

**Important remarks:**

- It is the responsibility of the user to verify they are accessing the latest version.